



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Applicant: Xiao-Chun Mu et al.

Title: PROCESS FOR FORMING A DIRECT BUILD-UP LAYER ON AN ENCAPSULATED DIE PACKAGES UTILIZING INTERMEDIATE STRUCTURES

Docket No.: 884.791US1  
Filed: September 14, 2000  
Examiner: Alonzo Chambliss

Serial No.: 09/661,899  
Due Date: May 14, 2007  
Group Art Unit: 2827

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

- ☒ Return postcard.
- ☒ A Check in the Amount of \$200.00 to Cover the Application for Patent Term Adjustment
- ☒ Application for Post Issue Patent Term Adjustment (1 pg.).
- ☒ Statement of Facts Unber 37 C.F.R. § 1.705(b)(2) In Support of Application For Post Issue Patent Term Adjustment (2 pgs.).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.  
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By: Ann M. McCrackin  
Atty: Ann M. McCrackin  
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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 14 day of May, 2007.

Chris Hammond  
Name

Chris Hammond  
Signature

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(GENERAL)